

LF155/LF156/LF256/LF257/LF355/LF356/LF357 JFET Input Operational Amplifiers

General Description

These are the first monolithic JFET input operational amplifiers to incorporate well matched, high voltage JFETs on the same chip with standard bipolar transistors (BI-FET™ Technology). These amplifiers feature low input bias and offset currents/low offset voltage and offset voltage drift, coupled with offset adjust which does not degrade drift or common-mode rejection. The devices are also designed for high slew rate, wide bandwidth, extremely fast settling time, low voltage and current noise and a low 1/f noise corner.

Features

Advantages

- Replace expensive hybrid and module FET op amps
- Rugged JFETs allow blow-out free handling compared with MOSFET input devices
- Excellent for low noise applications using either high or low source impedance—very low 1/f corner
- Offset adjust does not degrade drift or common-mode rejection as in most monolithic amplifiers
- New output stage allows use of large capacitive loads (5,000 pF) without stability problems
- Internal compensation and large differential input voltage capability

Applications

- Precision high speed integrators
- Fast D/A and A/D converters
- High impedance buffers
- Wideband, low noise, low drift amplifiers

Logarithmic amplifiers

- Photocell amplifiers
- Sample and Hold circuits

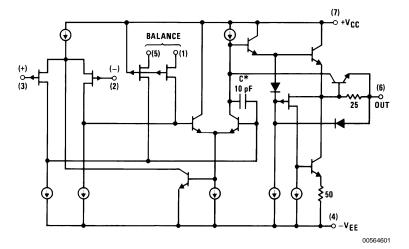
Common Features

- Low input bias current: 30pA
- Low Input Offset Current: 3pA
- High input impedance: $10^{12}\Omega$
- Low input noise current: $0.01 \text{ pA}/\sqrt{\text{Hz}}$
- High common-mode rejection ratio: 100 dB
- Large dc voltage gain: 106 dB

Uncommon Features

		LF155/ LF355	LF156/ LF256/ LF356	LF257/ LF357 (A _V =5)	Units
	Extremely fast settling time to 0.01%	4	1.5	1.5	μs
	Fast slew rate	5	12	50	V/µs
•	Wide gain bandwidth	2.5	5	20	MHz
	Low input noise voltage	20	12	12	nV/√Hz

Simplified Schematic



*3pF in LF357 series.

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, contact the National Semiconductor Sales Office/Distributors for availability and specifications.

	LF155/6	LF256/7/LF356B	LF355/6/7
Supply Voltage	±22V	±22V	±18V
Differential Input Voltage	±40V	±40V	±30V
Input Voltage Range (Note 2)	±20V	±20V	±16V
Output Short Circuit Duration	Continuous	Continuous	Continuous
T_{JMAX}			
H-Package	150°C	115°C	115°C
N-Package		100°C	100°C
M-Package		100°C	100°C
Power Dissipation at T _A = 25°C (Notes			
1, 8)			
H-Package (Still Air)	560 mW	400 mW	400 mW
H-Package (400 LF/Min Air Flow)	1200 mW	1000 mW	1000 mW
N-Package		670 mW	670 mW
M-Package		380 mW	380 mW
Thermal Resistance (Typical) θ_{JA}			
H-Package (Still Air)	160°C/W	160°C/W	160°C/W
H-Package (400 LF/Min Air Flow)	65°C/W	65°C/W	65°C/W
N-Package		130°C/W	130°C/W
M-Package		195°C/W	195°C/W
(Typical) θ_{JC}			
H-Package	23°C/W	23°C/W	23°C/W
Storage Temperature Range	-65°C to +150°C	-65°C to +150°C	-65°C to +150°C
Soldering Information (Lead Temp.)			
Metal Can Package			
Soldering (10 sec.)	300°C	300°C	300°C
Dual-In-Line Package			
Soldering (10 sec.)	260°C	260°C	260°C
Small Outline Package			
Vapor Phase (60 sec.)		215°C	215°C
Infrared (15 sec.)		220°C	220°C
See AN-450 "Surface Mounting Methods	and Their Effect on F	Product Reliability" for	other methods of
soldering surface mount devices.			
EOD telement			

ESD tolerance

(100 pF discharged through 1.5k Ω) 1000V 1000V 1000V

DC Electrical Characteristics

(Note 3)

Symbol	Parameter	Conditions	LF155/6			LF256/7 LF356B			ι	Units		
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Vos	Input Offset Voltage	$R_S=50\Omega$, $T_A=25^{\circ}C$		3	5		3	5		3	10	mV
		Over Temperature			7			6.5			13	mV
$\Delta V_{OS}/\Delta T$	Average TC of Input Offset Voltage	$R_S=50\Omega$		5			5			5		μV/°C
ΔTC/ΔV _{OS}	Change in Average TC with V _{OS} Adjust	$R_S=50\Omega$, (Note 4)		0.5			0.5			0.5		μV/°C per mV
I _{os}	Input Offset Current	T _J =25°C, (Notes 3, 5)		3	20		3	20		3	50	рА
T _J ≤T _{HIGH}		T _J ≤T _{HIGH}			20			1			2	nA

DC Electrical Characteristics (Continued)

(Note 3)

Symbol	Parameter	Conditions	LF155/6			LF256/7 LF356B			LF355/6/7			Units
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
I _B	Input Bias Current	T _J =25°C, (Notes 3, 5)		30	100		30	100		30	200	pА
		T _J ≤T _{HIGH}			50			5			8	nA
R _{IN}	Input Resistance	T _J =25°C		10 ¹²			10 ¹²			10 ¹²		Ω
A _{VOL}	Large Signal Voltage	V _S =±15V, T _A =25°C	50	200		50	200		25	200		V/mV
	Gain	$V_O = \pm 10V$, $R_L = 2k$										
		Over Temperature	25			25			15			V/mV
Vo	Output Voltage Swing	$V_S=\pm 15V, R_L=10k$	±12	±13		±12	±13		±12	±13		V
		$V_S=\pm 15V, R_L=2k$	±10	±12		±10	±12		±10	±12		V
V _{CM}	Input Common-Mode	V _S =±15V	±11	+15.1		±11	±15.1		+10	+15.1		V
	Voltage Range		-	-12		T 1 1	-12		+10	-12		V
CMRR	Common-Mode		85	100		85	100		80	100		dB
	Rejection Ratio		00	100		00	100		00	100		uБ
PSRR	Supply Voltage	(Note 6)	85	100		85	100		80	100		dB
	Rejection Ratio			100			1.00					QD

DC Electrical Characteristics

 $T_A = T_J = 25^{\circ}C, V_S = \pm 15V$

Parameter	LF155		LF355		LF156/256/257/356B		LF356		LF:	Units	
Faranietei	Тур	Max	Тур	Max	Тур	Max	Тур	Max	Тур	Max	Units
Supply Current	2	4	2	4	5	7	5	10	5	10	mA

AC Electrical Characteristics

 $T_A = T_J = 25^{\circ}C, V_S = \pm 15V$

			LF155/355	LF156/256/	LF156/256/356/	LF257/357	
Symbol	Parameter	Conditions		356B	LF356B		Units
			Тур	Min	Тур	Тур	
SR	Slew Rate	LF155/6:	5	7.5	12		V/µs
		A _V =1,					
		LF357: A _V =5				50	V/µs
GBW	Gain Bandwidth Product		2.5		5	20	MHz
t _s	Settling Time to 0.01%	(Note 7)	4		1.5	1.5	μs
e _n	Equivalent Input Noise	R _S =100Ω					
	Voltage	f=100 Hz	25		15	15	nV/√Hz
		f=1000 Hz	20		12	12	nV/√Hz
i _n	Equivalent Input Current	f=100 Hz	0.01		0.01	0.01	pA/√Hz
	Noise	f=1000 Hz	0.01		0.01	0.01	pA/√Hz
C _{IN}	Input Capacitance		3		3	3	pF

Notes for Electrical Characteristics

Note 1: The maximum power dissipation for these devices must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature, T_A . The maximum available power dissipation at any temperature is $P_D = (T_{JMAX} - T_A)/\theta_{JA}$ or the 25°C P_{dMAX} , whichever is less.

Note 2: Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.

Note 3: Unless otherwise stated, these test conditions apply:

Notes for Electrical Characteristics (Continued)

	LF155/156	LF256/257	LF356B	LF355/6/7
Supply Voltage, V _S	±15V ≤ V _S ≤ ±20V	±15V ≤ V _S ≤ ±20V	±15V ≤ V _S ±20V	V _S = ±15V
T_A	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$	$-25^{\circ}\text{C} \le \text{T}_{\text{A}} \le +85^{\circ}\text{C}$	$0^{\circ}\text{C} \le \text{T}_{\text{A}} \le +70^{\circ}\text{C}$	$0^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq +70^{\circ}\text{C}$
T _{HIGH}	+125°C	+85°C	+70°C	+70°C

and V_{OS} , I_B and I_{OS} are measured at $V_{CM} = 0$.

Note 4: The Temperature Coefficient of the adjusted input offset voltage changes only a small amount (0.5µV/°C typically) for each mV of adjustment from its original unadjusted value. Common-mode rejection and open loop voltage gain are also unaffected by offset adjustment.

Note 5: The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T_J . Due to limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, Pd. $T_J = T_A + \theta_{JA}$ Pd where θ_{JA} is the thermal resistance from junction to ambient. Use of a heat sink is recommended if input bias current is to be kept to a minimum.

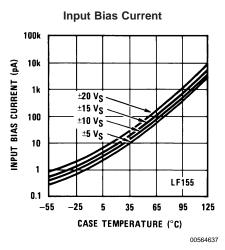
Note 6: Supply Voltage Rejection is measured for both supply magnitudes increasing or decreasing simultaneously, in accordance with common practice.

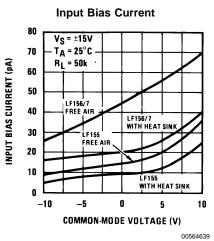
Note 7: Settling time is defined here, for a unity gain inverter connection using $2 k\Omega$ resistors for the LF155/6. It is the time required for the error voltage (the voltage at the inverting input pin on the amplifier) to settle to within 0.01% of its final value from the time a 10V step input is applied to the inverter. For the LF357, $A_V = -5$, the feedback resistor from output to input is $2k\Omega$ and the output step is 10V (See Settling Time Test Circuit).

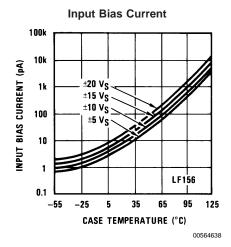
Note 8: Max. Power Dissipation is defined by the package characteristics. Operating the part near the Max. Power Dissipation may cause the part to operate outside quaranteed limits

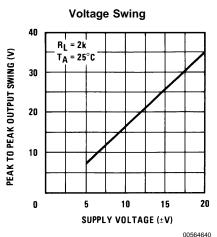
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Typical DC Performance Characteristics Curves are for LF155 and LF156 unless otherwise specified.



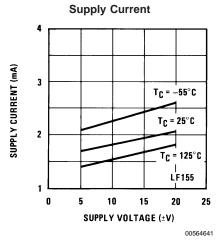




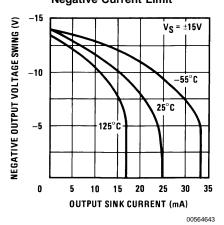


Typical DC Performance Characteristics Curves are for LF155 and LF156 unless otherwise

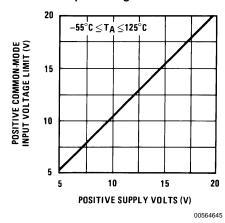
specified. (Continued)



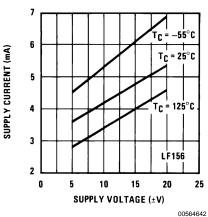
Negative Current Limit



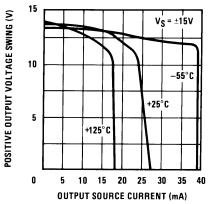
Positive Common-Mode Input Voltage Limit



Supply Current

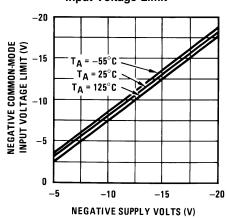


Positive Current Limit

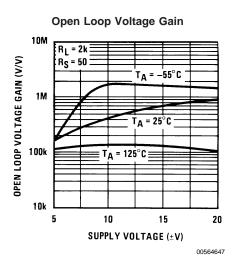


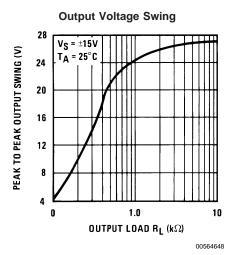
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Negative Common-Mode Input Voltage Limit

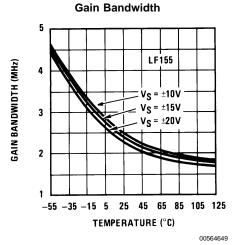


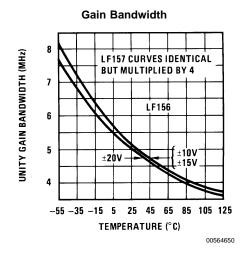
Typical DC Performance Characteristics Curves are for LF155 and LF156 unless otherwise specified. (Continued)

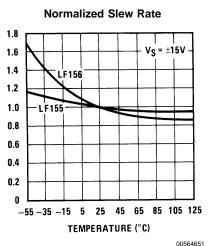


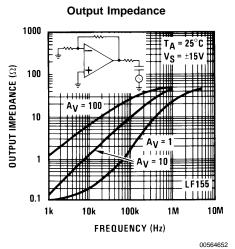


Typical AC Performance Characteristics



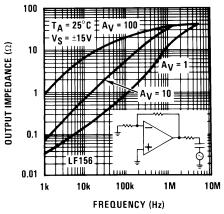






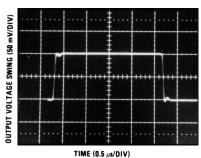
Typical AC Performance Characteristics (Continued)





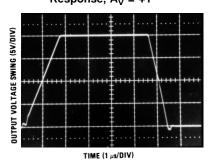
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LF156 Small Signal Pulse Response, $A_V = +1$



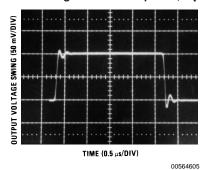
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LF156 Large Signal Puls Response, $A_V = +1$

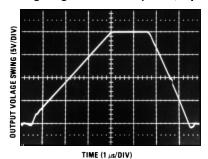


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LF155 Small Signal Pulse Response, $A_V = +1$

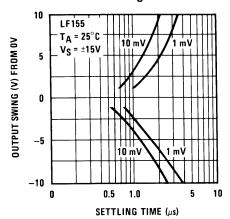


LF155 Large Signal Pulse Response, A_V = +1

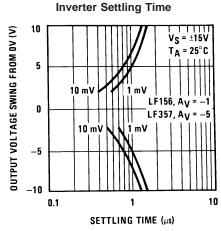


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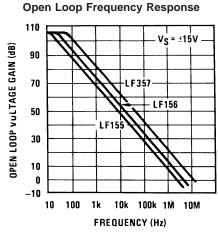
Inverter Settling Time



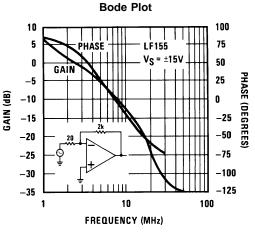
Typical AC Performance Characteristics (Continued)



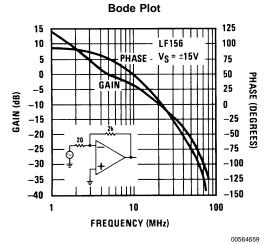
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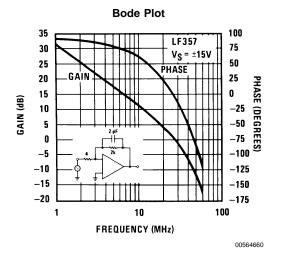
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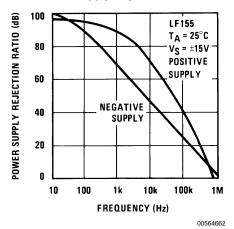


Common-Mode Rejection Ratio COMMON-MODE REJECTION RATIO (dB) V_S = ±15V R_L = 2k 80 T_A = 25°C 60 LF155/6 LF357 40 20 10 100 1k 10k 100k 1M 10M FREQUENCY (Hz)

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Typical AC Performance Characteristics (Continued)

Power Supply Rejection Ratio



POWER SUPPLY REJECTION RATIO (dB) 100 1k 100k 1M



FREQUENCY (Hz)

Power Supply Rejection Ratio

T_A = 25°C

V_S = ±15V

10M

POSITIVE SUPPLY

LF156/7

120

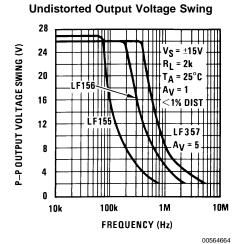
100

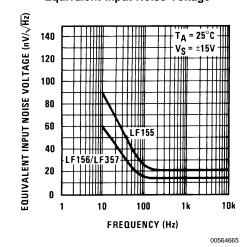
80

60

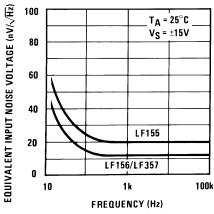
40

20



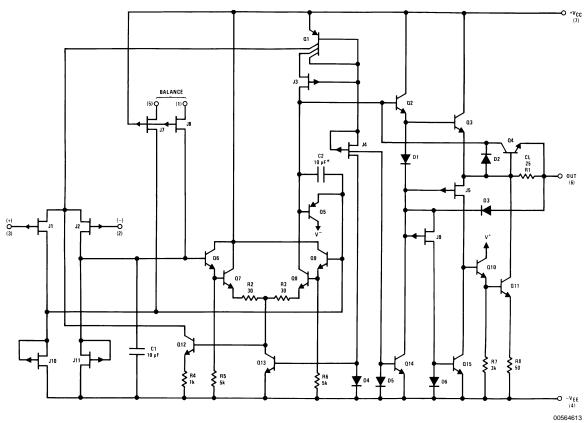


Equivalent Input Noise Voltage (Expanded Scale)



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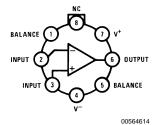
Detailed Schematic



*C = 3pF in LF357 series.

Connection Diagrams (Top Views)

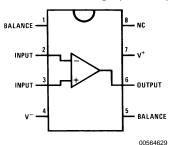
Metal Can Package (H)



Order Number LF155H, LF156H, LF256H, LF257H, LF356BH, LF356H, or LF357H See NS Package Number H08C

*Available per JM38510/11401 or JM38510/11402

Dual-In-Line Package (M and N)



Order Number LF356M, LF356MX, LF355N, or LF356N See NS Package Number M08A or N08E

Application Hints

These are op amps with JFET input devices. These JFETs have large reverse breakdown voltages from gate to source and drain eliminating the need for clamps across the inputs. Therefore large differential input voltages can easily be accommodated without a large increase in input current. The maximum differential input voltage is independent of the supply voltages. However, neither of the input voltages should be allowed to exceed the negative supply as this will cause large currents to flow which can result in a destroyed unit.

Exceeding the negative common-mode limit on either input will force the output to a high state, potentially causing a

Application Hints (Continued)

reversal of phase to the output. Exceeding the negative common-mode limit on both inputs will force the amplifier output to a high state. In neither case does a latch occur since raising the input back within the common-mode range again puts the input stage and thus the amplifier in a normal operating mode.

Exceeding the positive common-mode limit on a single input will not change the phase of the output however, if both inputs exceed the limit, the output of the amplifier will be forced to a high state.

These amplifiers will operate with the common-mode input voltage equal to the positive supply. In fact, the common-mode voltage can exceed the positive supply by approximately 100 mV independent of supply voltage and over the full operating temperature range. The positive supply can therefore be used as a reference on an input as, for example, in a supply current monitor and/or limiter.

Precautions should be taken to ensure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

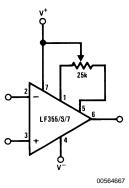
All of the bias currents in these amplifiers are set by FET current sources. The drain currents for the amplifiers are therefore essentially independent of supply voltage.

As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pickup" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground.

A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to AC ground set the frequency of the pole. In many instances the frequency of this pole is much greater than the expected 3dB frequency of the closed loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately six times the expected 3 dB frequency a lead capacitor should be placed from the output to the input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than or equal to the original feedback pole time constant.

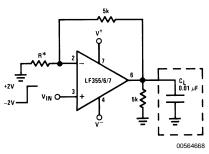
Typical Circuit Connections

Vos Adjustment



- V_{OS} is adjusted with a 25k potentiometer
- The potentiometer wiper is connected to V⁺
- For potentiometers with temperature coefficient of 100 ppm/°C or less the additional drift with adjust is $\approx 0.5 \mu V/$ °C/mV of adjustment
- Typical overall drift: 5µV/°C ±(0.5µV/°C/mV of adj.)

Driving Capacitive Loads



* LF155/6 R = 5k

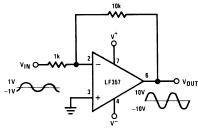
LF357 R = 1.25k

Due to a unique output stage design, these amplifiers have the ability to drive large capacitive loads and still maintain stability. $C_{L(MAX)} \simeq 0.01 \mu F$.

Overshoot ≤ 20%

Settling time $(t_s) \approx 5 \mu s$

LF357. A Large Power BW Amplifier

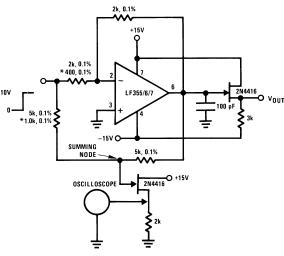


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For distortion \leq 1% and a 20 Vp-p V_{OUT} swing, power bandwidth is: 500kHz.

Typical Applications

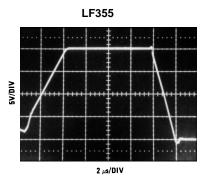
Settling Time Test Circuit



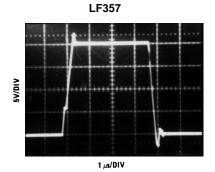
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- Settling time is tested with the LF155/6 connected as unity gain inverter and LF357 connected for $A_V = -5$
- FET used to isolate the probe capacitance
- Output = 10V step
- $A_V = -5$ for LF357

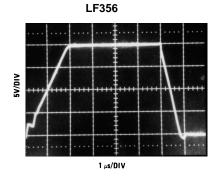
Large Signal Inverter Output, V_{OUT} (from Settling Time Circuit)



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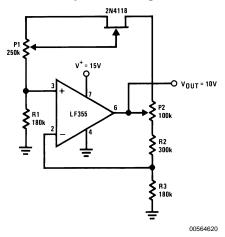


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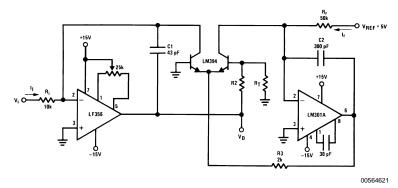
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Low Drift Adjustable Voltage Reference



- $\Delta V_{OUT}/\Delta T = \pm 0.002\%$ °C
- · All resistors and potentiometers should be wire-wound
- P1: drift adjust
- P2: V_{OUT} adjust
- · Use LF155 for
 - Low I_B
 - Low drift
 - Low supply current

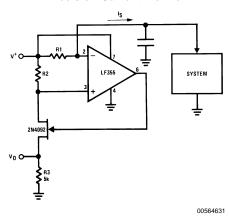
Fast Logarithmic Converter



- Dynamic range: $100\mu\text{A} \le I_i \le 1\text{mA}$ (5 decades), $|V_O| = 1\text{V/decade}$
- Transient response: $3\mu s$ for $\Delta l_i = 1$ decade
- · C1, C2, R2, R3: added dynamic compensation
- \bullet $\,$ $\,$ $\,$ $\,$ $\,$ $\,$ V $_{OS}$ adjust the LF156 to minimize quiescent error
- R_T: Tel Labs type Q81 + 0.3%/°C

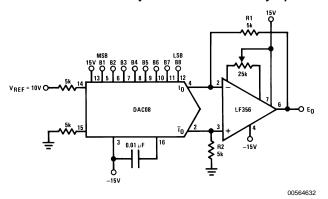
$$|V_{OUT}| = \left[1 + \frac{R2}{R_T}\right] \frac{kT}{q} \text{ in } V_i \left[\frac{R_r}{V_{REF~Ri}}\right] = log~V_i~\frac{1}{R_i I_r}~R2 = 15.7k,~R_T = 1k,~0.3\%/°C~(for~temperature~compensation)$$

Precision Current Monitor



- $V_O = 5 R1/R2 (V/mA of I_S)$
- R1, R2, R3: 0.1% resistors
- Use LF155 for
 - Common-mode range to supply range
 - Low I_B
 - Low V_{OS}
 - Low Supply Current

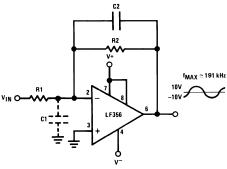
8-Bit D/A Converter with Symmetrical Offset Binary Operation



- R1, R2 should be matched within ±0.05%
- Full-scale response time: 3µs

Eo	В1	B2	В3	В4	B5	B6	В7	В8	Comments
+9.920	1	1	1	1	1	1	1	1	Positive Full-Scale
+0.040	1	0	0	0	0	0	0	0	(+) Zero-Scale
-0.040	0	1	1	1	1	1	1	1	(-) Zero-Scale
-9.920	0	0	0	0	0	0	0	0	Negative Full-Scale

Wide BW Low Noise, Low Drift Amplifier

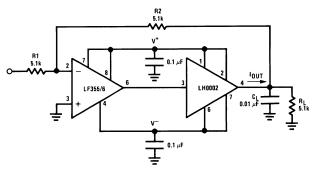


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• Power BW:
$$f_{MAX} = \frac{S_r}{2\pi V_p} \cong 191 \text{ kHz}$$

• Parasitic input capacitance C1 = (3pF for LF155, LF156 and LF357 plus any additional layout capacitance) interacts with feedback elements and creates undesirable high frequency pole. To compensate add C2 such that: R2 C2 = R1 C1.

Boosting the LF156 with a Current Amplifier



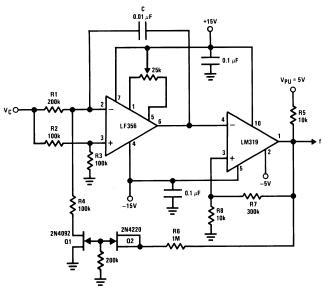
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• $I_{OUT(MAX)} \approx 150 mA$ (will drive $R_L \ge 100 \Omega$)

•
$$\frac{\Delta V_{OUT}}{\Delta T} = \frac{0.15}{10^{-2}} \text{ V/} \mu \text{s (with C}_{L} \text{ shown)}$$

· No additional phase shift added by the current amplifier

3 Decades VCO

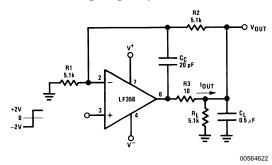


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$$f = \frac{V_{C} (R8 + R7)}{(8 V_{PU} R8 R1) C'} 0 \le V_{C} \le 30V, 10 Hz \le f \le 10 kHz$$

R1, R4 matched. Linearity 0.1% over 2 decades.

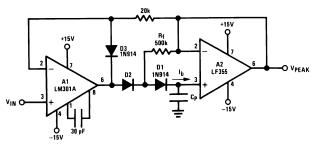
Isolating Large Capacitive Loads



- Overshoot 6%
- t_s 10µs
- When driving large C_L , the V_{OUT} slew rate determined by C_L and $I_{OUT(MAX)}$:

$$\frac{\Delta V_{\rm OUT}}{\Delta T} \,=\, \frac{I_{\rm OUT}}{C_{\rm L}} \,\cong\,\, \frac{0.02}{0.5} \, {\rm V}/\mu {\rm s} \,=\, 0.04 \, {\rm V}/\mu {\rm s} \,\, ({\rm with} \,\, C_{\rm L} \,\, {\rm shown})$$

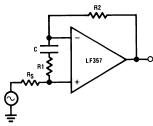
Low Drift Peak Detector



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- By adding D1 and R_f, V_{D1}=0 during hold mode. Leakage of D2 provided by feedback path through R_f.
- Leakage of circuit is essentially I_b (LF155, LF156) plus capacitor leakage of Cp.
- Diode D3 clamps V_{OUT} (A1) to $V_{IN}-V_{D3}$ to improve speed and to limit reverse bias of D2.
- Maximum input frequency should be << $1/2\pi R_f C_{D2}$ where C_{D2} is the shunt capacitance of D2.

Non-Inverting Unity Gain Operation for LF157



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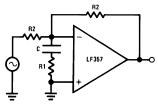
$$R1C \ge \frac{1}{(2\pi) (5 \text{ MHz})}$$

$$R1 = \frac{R2 + R_S}{4}$$

$$A_{V(DC)} = 1$$

$$f_{-3 \text{ dB}} \approx 5 \text{ MHz}$$

Inverting Unity Gain for LF157

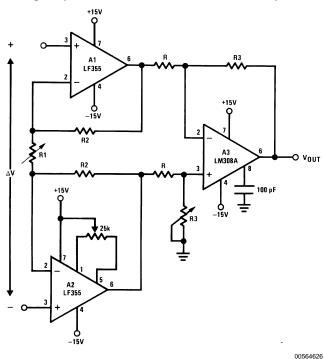


$$R1C \ge \frac{1}{(2\pi) (5 \text{ MHz})}$$

$$R1 = \frac{R2}{4}$$

$$f_{-3 dB} \approx 5 MHz$$

High Impedance, Low Drift Instrumentation Amplifier



•
$$V_{OUT} = \frac{R3}{R} \left[\frac{2R2}{R1} + 1 \right] \Delta V$$
, $V^- + 2V \le V_{IN}$ common-mode $\le V^+$

- System V_{OS} adjusted via A2 V_{OS} adjust
- Trim R3 to boost up CMRR to 120 dB. Instrumentation amplifier resistor array recommended for best accuracy and lowest drift

Fast Sample and Hold +15V 2cc pF R1 100k JFET SWITCHES SW2 A1 LF356 LF356 VOUT

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- · Both amplifiers (A1, A2) have feedback loops individually closed with stable responses (overshoot negligible)
- Acquisition time T_A, estimated by:

$$T_{A} \cong \left[\frac{2R_{ON}, V_{IN}, C_{h}}{S_{r}}\right] \frac{1}{2} \text{ provided that:}$$

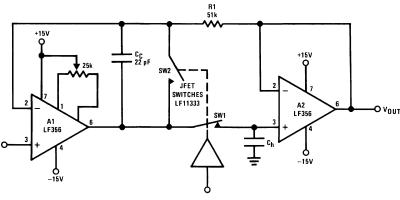
$$V_{IN}C_{h}$$

$$V_{IN}$$
 < $2\pi S_r R_{ON} C_h$ and T_A > $\frac{V_{IN} C_h}{I_{OUT(MAX)}}$, R_{ON} is of SW1

If inequality not satisfied:
$$T_A \simeq \frac{V_{IN}C_h}{20 \text{ mA}}$$

- LF156 develops full S_r output capability for $V_{IN} \ge 1V$
- Addition of SW2 improves accuracy by putting the voltage drop across SW1 inside the feedback loop
- Overall accuracy of system determined by the accuracy of both amplifiers, A1 and A2

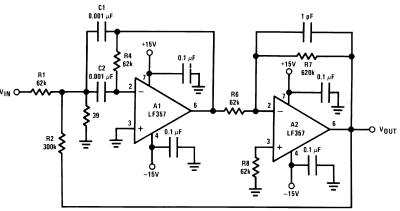
High Accuracy Sample and Hold



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- By closing the loop through A2, the V_{OUT} accuracy will be determined uniquely by A1.
 No V_{OS} adjust required for A2.
- T_A can be estimated by same considerations as previously but, because of the added propagation delay in the feedback loop (A2) the overshoot is not negligible.
- · Overall system slower than fast sample and hold
- R1, C_C: additional compensation
- Use LF156 for
 - Fast settling time
 - Low V_{os}

High Q Band Pass Filter



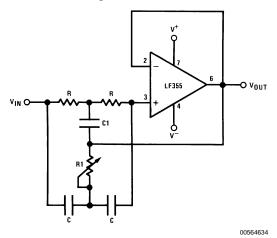
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- By adding positive feedback (R2)
- Q increases to 40
- f_{BP} = 100 kHz

$$\frac{V_{OUT}}{V_{IN}} = 10\sqrt{\overline{Q}}$$

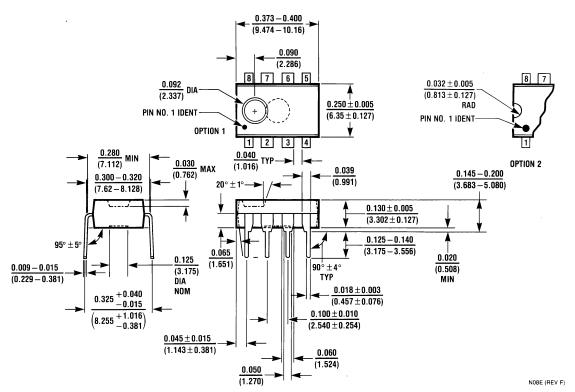
- Clean layout recommended
- Response to a 1Vp-p tone burst: 300µs

High Q Notch Filter



- $2R1 = R = 10M\Omega$ 2C = C1 = 300pF
- · Capacitors should be matched to obtain high Q
- $f_{NOTCH} = 120 \text{ Hz}, \text{ notch} = -55 \text{ dB}, Q > 100$
- Use LF155 for
 - Low I_B
 - Low supply current

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Molded Dual-In-Line Package (N) Order Number LF356N NS Package Number N08E

LIFE SUPPORT POLICY

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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



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LF147/LF347

Wide Bandwidth Quad JFET Input Operational Amplifiers

General Description

The LF147 is a low cost, high speed quad JFET input operational amplifier with an internally trimmed input offset voltage (BI-FET II™ technology). The device requires a low supply current and yet maintains a large gain bandwidth product and a fast slew rate. In addition, well matched high voltage JFET input devices provide very low input bias and offset currents. The LF147 is pin compatible with the standard LM148. This feature allows designers to immediately upgrade the overall performance of existing LF148 and LM124 designs.

The LF147 may be used in applications such as high speed integrators, fast D/A converters, sample-and-hold circuits and many other circuits requiring low input offset voltage, low input bias current, high input impedance, high slew rate and wide bandwidth. The device has low noise and offset voltage drift.

Features

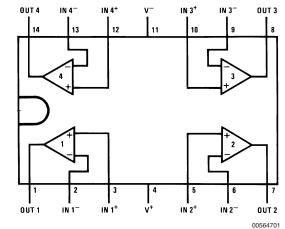
Internally trimmed offset voltage:Low input bias current:	5 mV max 50 pA
■ Low input noise current:	0.01 pA/√Hz
Wide gain bandwidth:High slew rate:	4 MHz 13 V/μs
Low supply current:High input impedance:	7.2 mA 10 ¹² Ω
■ Low total harmonic distortion:	≤0.02%
Low 1/f noise corner:Fast settling time to 0.01%:	50 Hz 2 μs

Simplified Schematic

VCC O VO VO INTERNALLY TRIMMED TRIMMED O0564713

Connection Diagram

Dual-In-Line Package



Note 1: LF147 available as per JM38510/11906.

Top View

Order Number LF147J, LF147J-SMD, LF347M, LF347BN, LF347N, LF147J/883, or JL147 BCA (Note 1)
See NS Package Number J14A, M14A or N14A

BI-FET II™ is a trademark of National Semiconductor Corporation.

Absolute Maximum Ratings (Note 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

	LF147	LF347B/LF347
Supply Voltage	±22V	±18V
Differential Input Voltage	±38V	±30V
Input Voltage Range	±19V	±15V
(Note 3)		
Output Short Circuit	Continuous	Continuous
Duration (Note 4)		
Power Dissipation	900 mW	1000 mW
(Notes 5, 11)		
T _j max	150°C	150°C
θ_{jA}		
Ceramic DIP (J) Package		70°C/W
Plastic DIP (N) Package		75°C/W
Surface Mount Narrow (M)		100°C/W
Surface Mount Wide (WM)		85°C/W

	LF147	LF347B/LF347
Operating Temperature	(Note 6)	(Note 6)

Range

Storage Temperature

Range $-65^{\circ}\text{C} \le \text{T}_{A} \le 150^{\circ}\text{C}$

Lead Temperature

(Soldering, 10 sec.) 260°C 260°C

Soldering Information

Dual-In-Line Package

Soldering (10 seconds) 260°C

Small Outline Package

Vapor Phase (60 seconds) 215°C Infrared (15 seconds) 220°C

See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering

surface mount devices.

ESD Tolerance (Note 12) 900V

DC Electrical Characteristics (Note 7)

Symbol	Parameter	Conditions		LF147			LF347E	3		LF347		Units
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
V _{os}	Input Offset Voltage	R _S =10 kΩ, T _A =25°C		1	5		3	5		5	10	mV
		Over Temperature			8			7			13	mV
$\Delta V_{OS}/\Delta T$	Average TC of Input Offset	R _S =10 kΩ		10			10			10		μV/°C
	Voltage											
I _{os}	Input Offset Current	T _j =25°C, (Notes 7, 8)		25	100		25	100		25	100	pА
		Over Temperature			25			4			4	nA
I _B	Input Bias Current	T _j =25°C, (Notes 7, 8)		50	200		50	200		50	200	pА
		Over Temperature			50			8			8	nA
R _{IN}	Input Resistance	T _j =25°C		10 ¹²			10 ¹²			10 ¹²		Ω
A _{VOL}	Large Signal Voltage Gain	V _S =±15V, T _A =25°C	50	100		50	100		25	100		V/mV
		$V_O=\pm 10V$, $R_L=2 k\Omega$										
		Over Temperature	25			25			15			V/mV
Vo	Output Voltage Swing	$V_S=\pm 15V$, $R_L=10 \text{ k}\Omega$	±12	±13.5		±12	±13.5		±12	±13.5		V
V _{CM}	Input Common-Mode Voltage	V _S =±15V	±11	+15		±11	+15		±11	+15		V
	Range			-12			-12			-12		V
CMRR	Common-Mode Rejection Ratio	R _S ≤10 kΩ	80	100		80	100		70	100		dB
PSRR	Supply Voltage Rejection Ratio	(Note 9)	80	100		80	100		70	100		dB
Is	Supply Current			7.2	11		7.2	11		7.2	11	mA

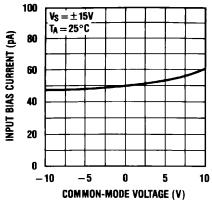
AC Electrical Characteristics (Note 7)

Symbol	Parameter	Conditions		LF147	,	ı	LF347E	3		LF347		Units
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	Amplifier to Amplifier Coupling	T _A =25°C,		-120			-120			-120		dB
		f=1 Hz-20 kHz										
		(Input Referred)										
SR	Slew Rate	V _S =±15V, T _A =25°C	8	13		8	13		8	13		V/µs
GBW	Gain-Bandwidth Product	V _S =±15V, T _A =25°C	2.2	4		2.2	4		2.2	4		MHz
e _n	Equivalent Input Noise Voltage	$T_A=25$ °C, $R_S=100\Omega$,		20			20			20		nV/√ Hz
		f=1000 Hz										
i _n	Equivalent Input Noise Current	T _j =25°C, f=1000 Hz		0.01			0.01			0.01		pA/√ Hz
THD	Total Harmonic Distortion	A _V =+10, R _L =10k,		<0.02			<0.02			<0.02		%
		V _O =20 Vp-p, BW=20 Hz-20 kHz										

- Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.
- Note 3: Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.
- **Note 4:** Any of the amplifier outputs can be shorted to ground indefinitely, however, more than one should not be simultaneously shorted as the maximum junction temperature will be exceeded.
- Note 5: For operating at elevated temperature, these devices must be derated based on a thermal resistance of θ_{jA} .
- Note 6: The LF147 is available in the military temperature range $-55^{\circ}C \le T_{A} \le 125^{\circ}C$, while the LF347B and the LF347 are available in the commercial temperature range $0^{\circ}C \le T_{A} \le 70^{\circ}C$. Junction temperature can rise to T_{i} max = 150°C.
- Note 7: Unless otherwise specified the specifications apply over the full temperature range and for $V_S=\pm20V$ for the LF147 and for $V_S=\pm15V$ for the LF347B/LF347. V_{OS} , I_B , and I_{OS} are measured at $V_{CM}=0$.
- Note 8: The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T_j . Due to limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, P_D . $T_j = T_A + \theta_{jA}$ P_D where θ_{jA} is the thermal resistance from junction to ambient. Use of a heat sink is recommended if input bias current is to be kept to a minimum.
- Note 9: Supply voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously in accordance with common practice from $V_S = \pm 5V$ to $\pm 15V$ for the LF347 and LF347B and from $V_S = \pm 20V$ to $\pm 5V$ for the LF147.
- Note 10: Refer to RETS147X for LF147D and LF147J military specifications.
- Note 11: Max. Power Dissipation is defined by the package characteristics. Operating the part near the Max. Power Dissipation may cause the part to operate outside guaranteed limits.
- Note 12: Human body model, 1.5 k Ω in series with 100 pF.

Typical Performance Characteristics





TEMPERATURE (°C)

0 25 50 75

Input Bias Current

100k

10k

1k

100

10

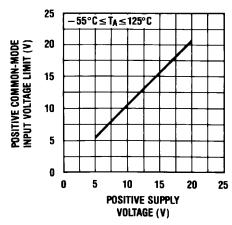
-50 - 25

INPUT BIAS CURRENT (pA)

 $V_{CM} = 0$

 $V_S = \pm 15V$

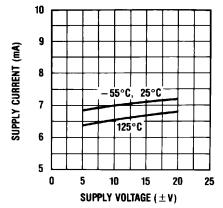




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100 125

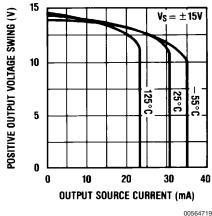
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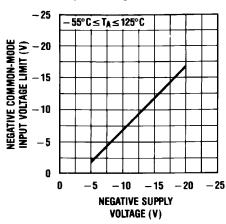
Supply Current

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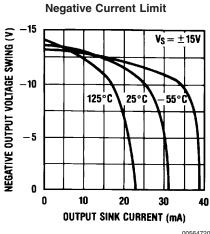
Positive Current Limit

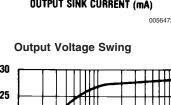


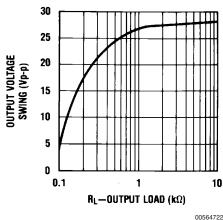


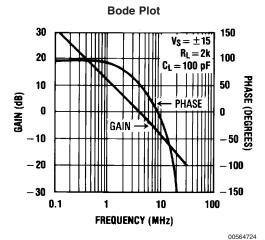


Typical Performance Characteristics (Continued)

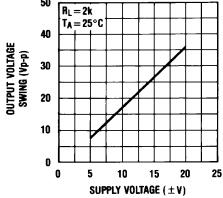






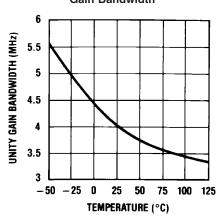


Output Voltage Swing RL=2k



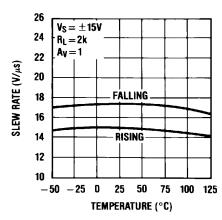
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Gain Bandwidth

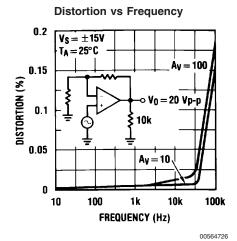


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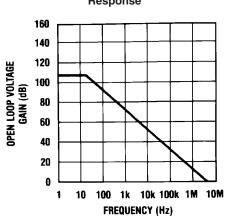
Slew Rate



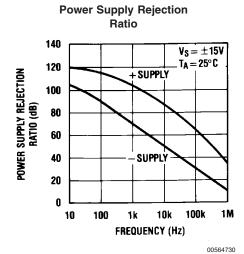
Typical Performance Characteristics (Continued)



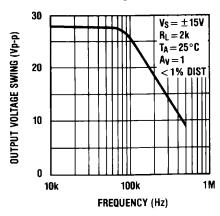
Open Loop Frequency Response



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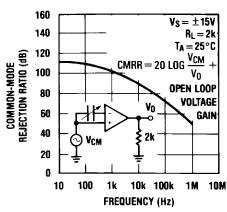


Undistorted Output Voltage Swing



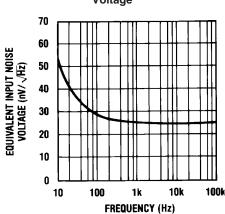
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Common-Mode Rejection



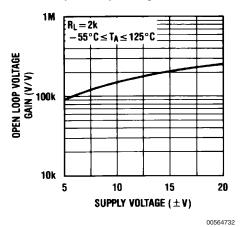
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Equivalent Input Noise Voltage

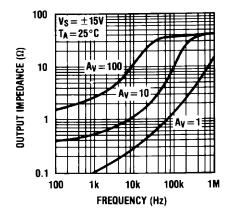


Typical Performance Characteristics (Continued)

Open Loop Voltage Gain

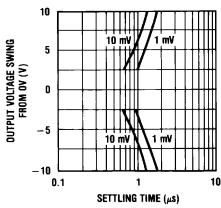


Output Impedance



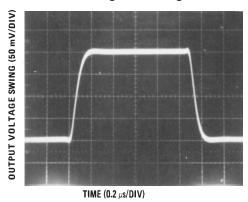
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Inverter Settling Time

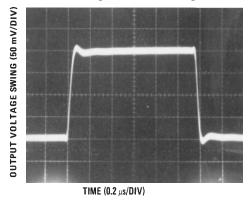


Pulse Response $R_L=2 \text{ k}\Omega, C_L=10 \text{ pF}$

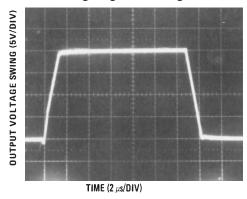
Small Signal Inverting



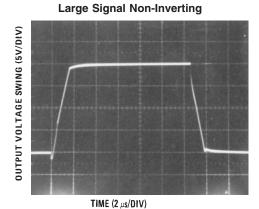
Small Signal Non-Inverting



Large Signal Inverting

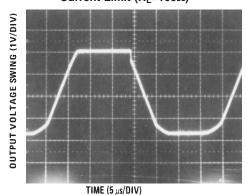


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Current Limit (R_L=100Ω)



0056470

Application Hints

The LF147 is an op amp with an internally trimmed input offset voltage and JFET input devices (BI-FET II). These JFETs have large reverse breakdown voltages from gate to source and drain eliminating the need for clamps across the inputs. Therefore, large differential input voltages can easily be accommodated without a large increase in input current. The maximum differential input voltage is independent of the supply voltages. However, neither of the input voltages

should be allowed to exceed the negative supply as this will cause large currents to flow which can result in a destroyed unit.

Exceeding the negative common-mode limit on either input will force the output to a high state, potentially causing a reversal of phase to the output. Exceeding the negative common-mode limit on both inputs will force the amplifier output to a high state. In neither case does a latch occur since raising the input back within the common-mode range again puts the input stage and thus the amplifier in a normal operating mode.

Application Hints (Continued)

Exceeding the positive common-mode limit on a single input will not change the phase of the output; however, if both inputs exceed the limit, the output of the amplifier will be forced to a high state.

The amplifiers will operate with a common-mode input voltage equal to the positive supply; however, the gain bandwidth and slew rate may be decreased in this condition. When the negative common-mode voltage swings to within 3V of the negative supply, an increase in input offset voltage may occur.

Each amplifier is individually biased by a zener reference which allows normal circuit operation on $\pm 4.5 \text{V}$ power supplies. Supply voltages less than these may result in lower gain bandwidth and slew rate.

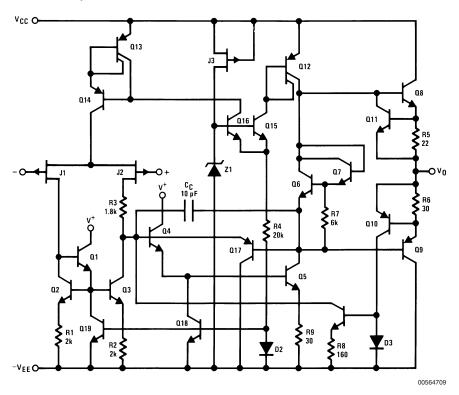
The LF147 will drive a 2 k Ω load resistance to $\pm 10V$ over the full temperature range. If the amplifier is forced to drive heavier load currents, however, an increase in input offset voltage may occur on the negative voltage swing and finally reach an active current limit on both positive and negative swings.

Precautions should be taken to ensure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pick-up" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground.

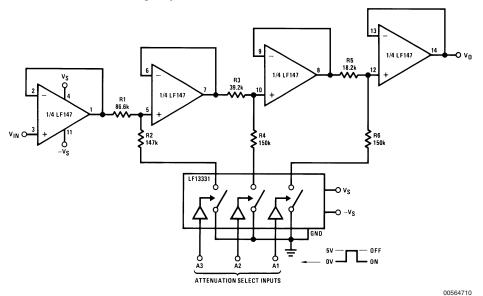
A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to AC ground set the frequency of the pole. In many instances the frequency of this pole is much greater than the expected 3 dB frequency of the closed loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately 6 times the expected 3 dB frequency a lead capacitor should be placed from the output to the input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than or equal to the original feedback pole time constant.

Detailed Schematic



Typical Applications

Digitally Selectable Precision Attenuator

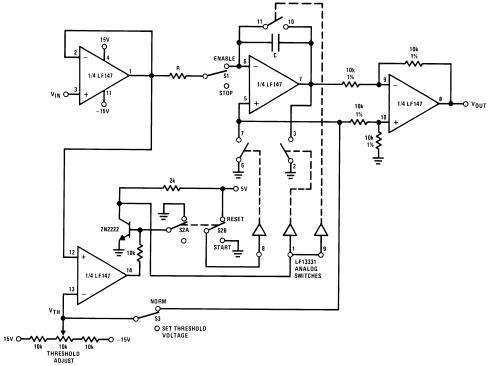


All resistors 1% tolerance

- Accuracy of better than 0.4% with standard 1% value resistors
 No offset adjustment necessary
- Expandable to any number of stages
- Very high input impedance

A 1	A2	А3	Vo
			Attenuation
0	0	0	0
0	0	1	–1 dB
0	1	0	–2 dB
0	1	1	-3 dB
1	0	0	-4 dB
1	0	1	–5 dB
1	1	0	−6 dB
1	1	1	–7 dB

Long Time Integrator with Reset, Hold and Starting Threshold Adjustment



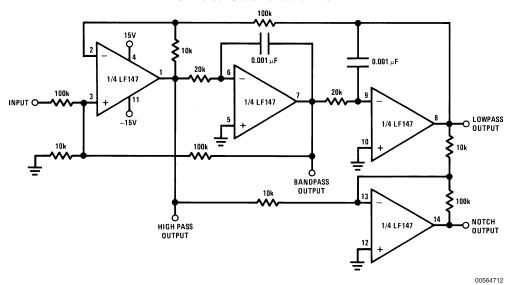
0564711

 \bullet V_{OUT} starts from zero and is equal to the integral of the input voltage with respect to the threshold voltage:

$$V_{OUT} = \frac{1}{RC} \int_0^t (V_{IN} - V_{TH}) dt$$

- Output starts when V_{IN}≥V_{TH}
- Switch S1 permits stopping and holding any output value
- Switch S2 resets system to zero

Universal State Variable Filter



For circuit shown:

 $f_0=3$ kHz, $f_{NOTCH}=9.5$ kHz

 $\Omega = 3.4$

Passband gain:

Highpass — 0.1

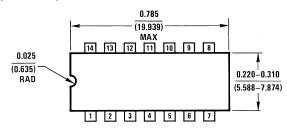
Bandpass — 1

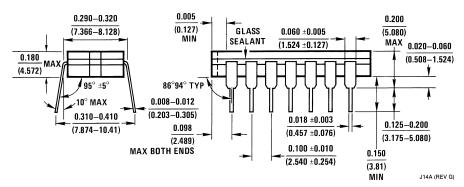
Lowpass — 1

Notch — 10

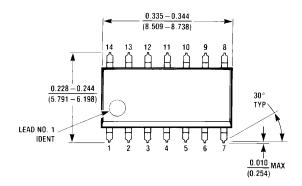
- f_oxQ≤200 kHz
- 10V peak sinusoidal output swing without slew limiting to 200 kHz
- See LM148 data sheet for design equations

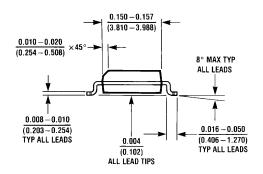
Physical Dimensions inches (millimeters) unless otherwise noted

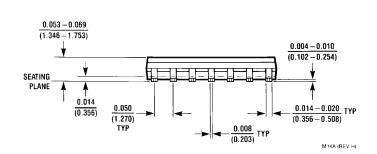




Ceramic Dual-In-Line Package (J)
Order Number LF147J, LM147J-SMD or LF147J/883
NS Package Number J14A

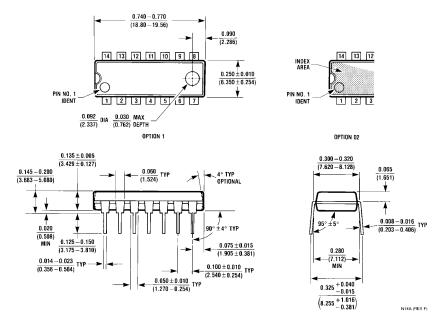






S.O. Package (M)
Order Number LF347M or LF347MX
NS Package Number M14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Molded Dual-In-Line Package (N) Order Number LF347BN or LF347N NS Package Number N14A

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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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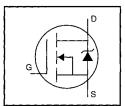
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HEXFET® Power MOSFET

- Isolated Package
- High Voltage Isolation= 2.5KVRMS ⑤
- Sink to Lead Creepage Dist.= 4.8mm
- 175°C Operating Temperature
- Dynamic dv/dt Rating
- Low Thermal Resistance

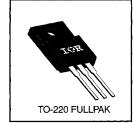


 $V_{DSS} = 60V$ $R_{DS(on)} = 0.20\Omega$ $I_{D} = 8.0A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 Fullpak eliminates the need for additional insulating hardware in commercial-industrial applications. The moulding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The Fullpak is mounted to a heatsink using a single clip or by a single screw fixing.



Absolute Maximum Ratings

	Parameter	Max.	Units
lp @ Tc ≈ 25°C	Continuous Drain Current, V _{GS} @ 10 V	8.0	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10 V	5.7	Α
[DM	Pulsed Drain Current ①	32	
P _D @ T _C = 25°C	Power Dissipation	27	W
	Linear Derating Factor	0.18	W/°C
V _{GS}	Gate-to-Source Voltage	±20	V
Eas	Single Pulse Avalanche Energy ②	47	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.5	V/ns
TJ	Operating Junction and	-55 to +175	
T _{STG}	Storage Temperature Range		∘c
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	

Thermal Resistance

	Parameter	Min.	Тур.	Max.	Units
Rыc	Junction-to-Case			5.5	°C/W
Reia	Junction-to-Ambient		_	65	-0/00



Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Test Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	60	_	_	V	V _{GS} =0V, I _D = 250μA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	_	0.63	_	V/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	_	_	0.20	Ω	V _{GS} =10V, I _D =4.8A ④
V _{GS(th)}	Gate Threshold Voltage	2.0	_	4.0	٧	V _{DS} =V _{GS} , I _D = 250μA
g _{fs}	Forward Transconductance	2.2	_	_	S	V _{DS} =25V, I _D =4.8A ⊕
Ipss	Drain-to-Source Leakage Current	_		25	μΑ	V _{DS} =60V, V _{GS} =0V
SSUI	Dialif-to-Cource Leakage Outrent			250	μΑ	V _{DS} =48V, V _{GS} =0V, T _J =150°C
I _{GSS}	Gate-to-Source Forward Leakage			100	nΑ	V _{GS} =20V
IGSS	Gate-to-Source Reverse Leakage			-100	110	V _{GS} =-20V
Qg	Total Gate Charge		_	11	ļ	I _D =10A
Q _{gs}	Gate-to-Source Charge			3.1	nC	V _{DS} =48V
Q_{gd}	Gate-to-Drain ("Miller") Charge	<u> </u>	_	5.8		V _{GS} =10V See Fig. 6 and 13 ®
t _{d(on)}	Turn-On Delay Time	<u></u>	10			V _{DD} =30V
t _r	Rise Time		50		ns	I _D =10A
t _{d(off)}	Turn-Off Delay Time	<u> </u>	13		110	$R_{G}=24\Omega$
tf	Fall Time		19	_		R _D =2.7Ω See Figure 10 @
L _D	Internal Drain Inductance	_	4.5		nН	Between lead, 6 mm (0.25in.)
Ls	Internal Source Inductance	_	7.5	_	,,,,	from package and center of die contact
Ciss	Input Capacitance		300	_		V _{GS} =0V
Coss	Output Capacitance		160		pF	V _{DS} = 25V
Crss	Reverse Transfer Capacitance	_	29	_		f=1.0MHz See Figure 5
С	Drain to Sink Capacitance	_	12	_	рF	f=1.0MHz

Source-Drain Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Test Conditions		
ls	Continuous Source Current (Body Diode)	_	_	8.0		MOSFET symbol showing the		
Ism	Pulsed Source Current (Body Diode) ①		_	32	A	integral reverse p-n junction diode.		
V _{SD}	Diode Forward Voltage	_ _	_	1.6	V	T _J =25°C, I _S =8.0A, V _{GS} =0V ④		
t _{rr}	Reverse Recovery Time		70	140	ns	T _J =25°C, I _F =10A		
Qrr	Reverse Recovery Charge	_	0.20	0.40	μC	di/dt=100A/μs ④		
ton	Forward Turn-On Time	Intrinsi	Intrinsic turn-on time is neglegible (turn-on is dominated by Ls+LD)					

Notes:

- Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ③ I_{SD} ≤10A, di/dt≤90A/ μ s, V_{DD} ≤ $V_{(BR)DSS}$, T_{J} ≤175°C
- \$ t=60s, f=60Hz

- $V_{DD}=25V$, starting T_J=25°C, L=856μH R_G=25Ω, I_{AS}=8.0A (See Figure 12)
- 4 Pulse width \leq 300 μ s; duty cycle \leq 2%.

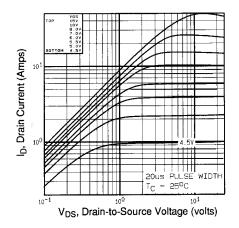


Fig 1. Typical Output Characteristics, T_C=25°C

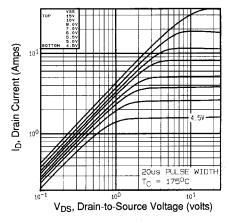


Fig 2. Typical Output Characteristics, T_C=175°C

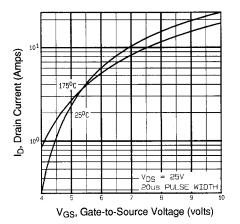


Fig 3. Typical Transfer Characteristics

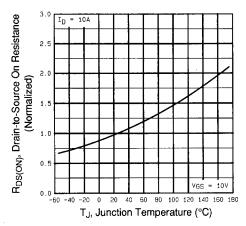


Fig 4. Normalized On-Resistance Vs. Temperature

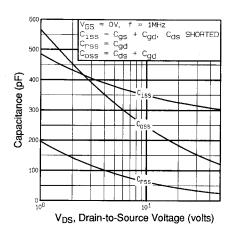


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

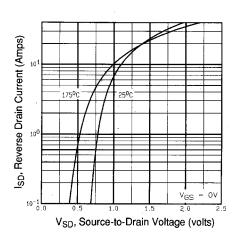


Fig 7. Typical Source-Drain Diode Forward Voltage

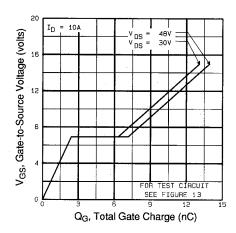


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

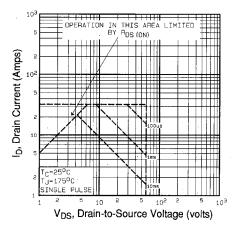


Fig 8. Maximum Safe Operating Area

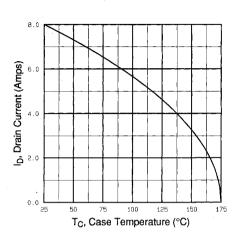


Fig 9. Maximum Drain Current Vs. Case Temperature

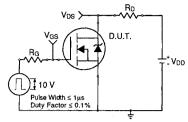


Fig 10a. Switching Time Test Circuit

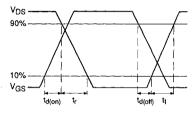


Fig 10b. Switching Time Waveforms

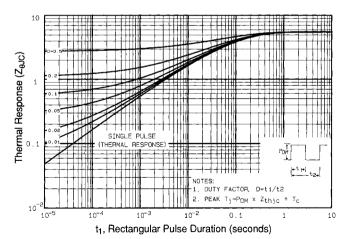


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

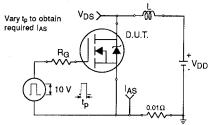


Fig 12a. Unclamped Inductive Test Circuit

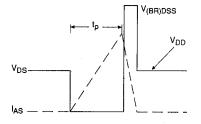


Fig 12b. Unclamped Inductive Waveforms

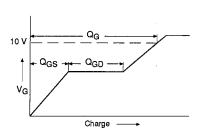


Fig 13a. Basic Gate Charge Waveform

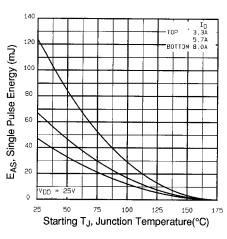


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

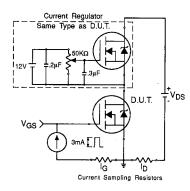


Fig 13b. Gate Charge Test Circuit

Appendix A: Figure 14, Peak Diode Recovery dv/dt Test Circuit - See page 1505

Appendix B: Package Outline Mechanical Drawing - See page 1510

Appendix C: Part Marking Information – See page 1517



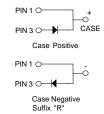


FES16AT - FES16JT

Features

- Low forward voltage drop.
- High surge current capacity.
- High current capability.
- High reliability.





Fast Rectifiers (Glass Passivated)

Absolute Maximum Ratings*

T_A = 25°C unless otherwise noted

Symbol	Parameter	Value								Units
		16AT	16BT	16CT	16DT	16FT	16GT	16HT	16JT	
V_{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	300	400	500	600	V
I _{F(AV)}	Average Rectified Forward Current, .375 " lead length @ T _A = 100°C		16							
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	250								А
T _{sta}	Storage Temperature Range				-65 to	+150				V
TJ	Operating Junction Temperature				-65 to	+150				pF

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P_{D}	Power Dissipation	7.81	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	16	°C/W
$R_{\theta JL}$	Thermal Resistance, Junction to Lead	1.2	°C/W

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Device								Units
		16AT	16BT	16CT	16DT	16FT	16GT	16HT	16JT	
V _F	Forward Voltage @ 8.0A	0.95 1.3						1	.5	V
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$		35	;			ns			
I _R	Reverse Current @ rated V_R $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$	10 500							μΑ μΑ	
Ст	Total Capacitance $V_R = 4.0$. $f = 1.0$ MHz	170 145						pF		

Typical Characteristics

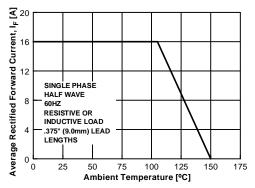


Figure 1. Forward Current Derating Curve

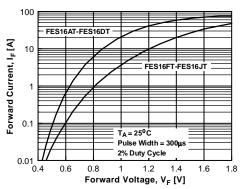


Figure 3. Forward Voltage Characteristics

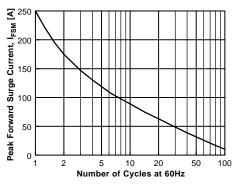


Figure 2. Non-Repetitive Surge Current

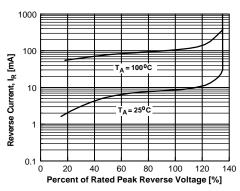


Figure 4. Reverse Current vs Reverse Voltage

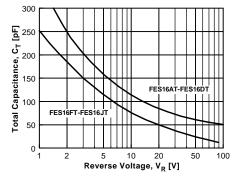
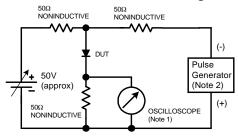
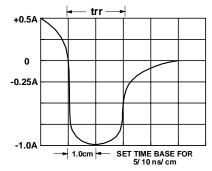


Figure 5. Total Capacitance





Reverse Recovery Time Characterstic and Test Circuit Diagram